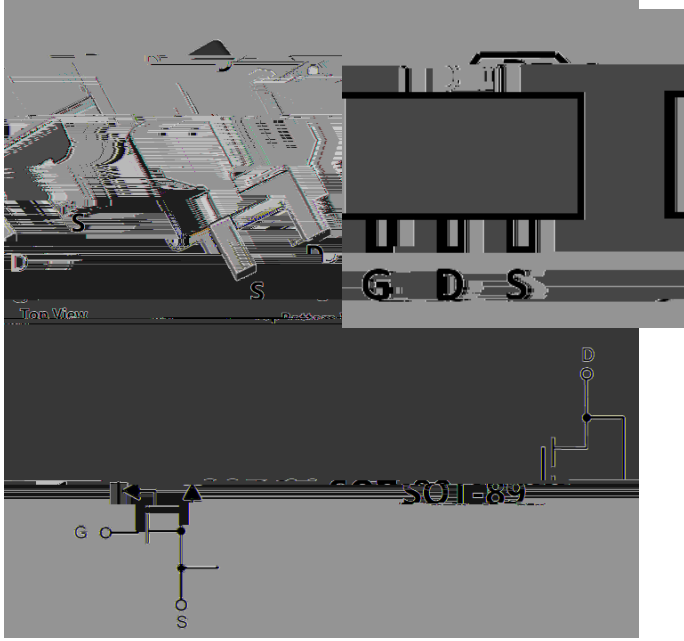




N-Channel Enhancement Mode Field Effect Transistor



Product Summary

V_{DS}	60V
I_D	3.5A
$R_{DS(ON)}$ (at $V_{GS}= 10V$)	100mohm
$R_{DS(ON)}$ (at $V_{GS}= 4.5V$)	120mohm
$R_{DS(ON)}$ (at $V_{GS}= 2.5V$)	200mohm

General Description

Trench Power LV MOSFET technology
 High Density Cell Design for Low $R_{DS(ON)}$
 High Speed switching
 Epoxy Meets UL 94 V-0 Flammability Rating
 Halogen Free

Applications

Battery protection
 Load switch
 Power management

Absolute Maximum Ratings ($T_A=25$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-source Voltage	V_{DS}	60	V
Gate-source Voltage	V_{GS}	± 16	V

Drain Current $T_A=25$ I_D 3.5 Thermal Resistance Junction to Case $R_{\theta JC}$

R_{JA}	74	/ W
Junction and Storage Temperature Range	T_J, T_{STG}	-55 +150

Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJH03N06B	F1	6003	1000	10000	40000	7" reel
	F2	6003	1000	8000	32000	7" reel



YJH03N06B

Electrical Characteristics (T_J=25 unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =-250μA	60			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 60V, V _{GS} =0V			1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±16V, V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	0.65	0.95	1.55	V
Static Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 3A		86	100	m
		V _{GS} = 4.5V, I _D = 2A		90	120	
		V _{GS} = 2.5V, I _D = 1A		100	200 = 10V, V	
Diode Forward Voltage	V _{SD}	I _S = 3.0A, V _{GS} =0V		0.8	1.2	V
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{DS} =30V, V _{GS} =0V, f=1MHZ		451		pF
Output Capacitance	C _{oss}			38		
Reverse Transfer Capacitance	C _{rss}			31		
Switching Parameters						
Total Gate Charge	Q _g	V _{GS} = 10V, V _{DS} = 30V, I _D = 3.0A		13.8		nC
Gate-Source Charge	Q _{gs}			2.2		
Gate-Drain Charge	Q _{gd}			1.9		
Reverse Recovery Chrage	Q _{rr}	I _F = 3A, di/dt=100A/us		7.6		ns
Reverse Recovery Time	t _{rr}			30		



Typical Performance Characteristics

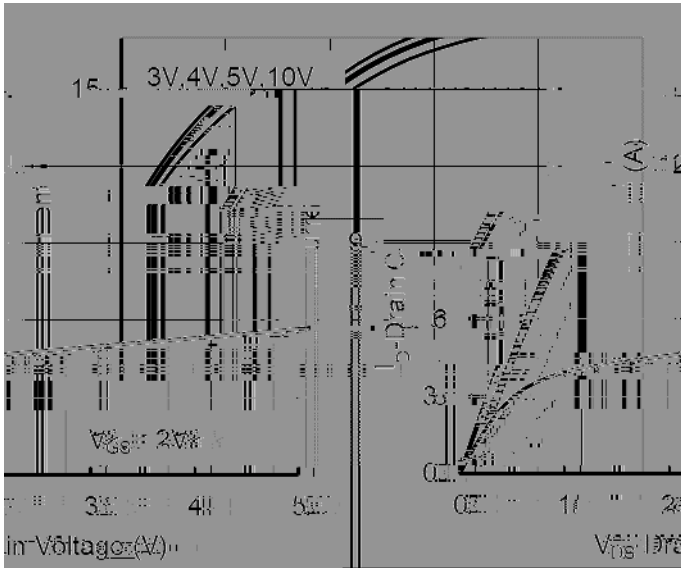


Figure1. Output Characteristics

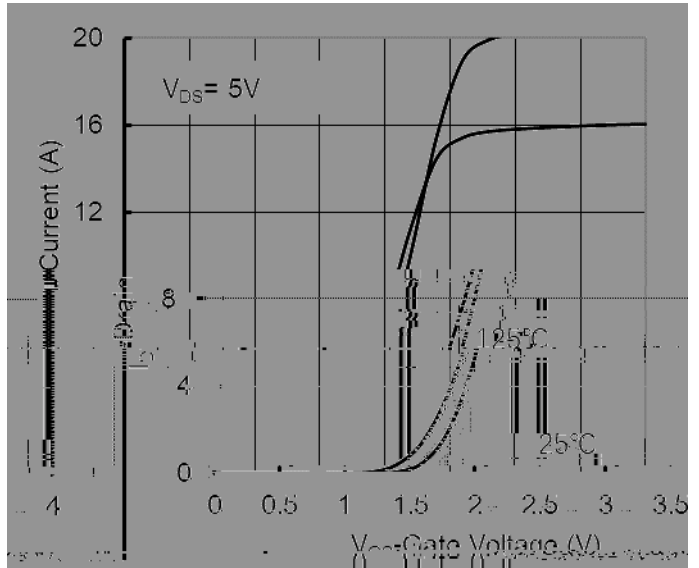


Figure2. Transfer Characteristics

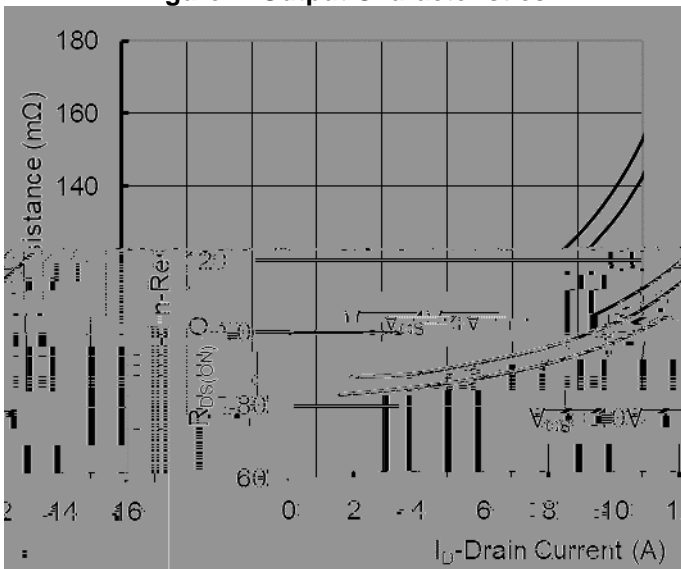


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

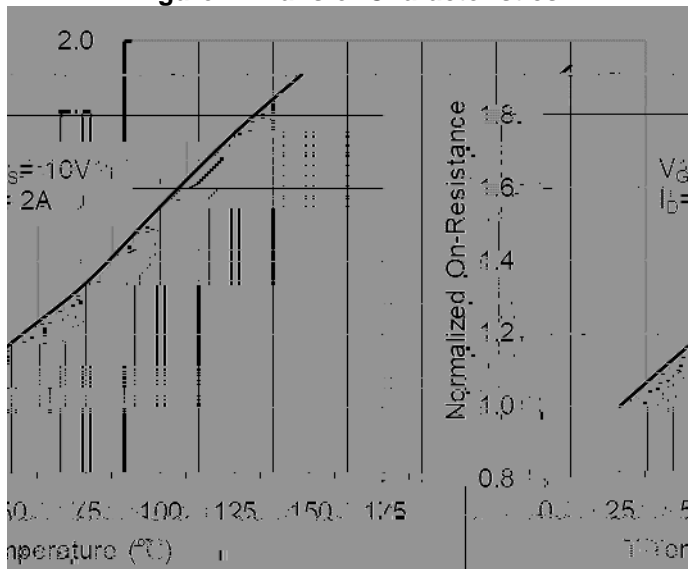


Figure 4: On-Resistance vs. Junction Temperature

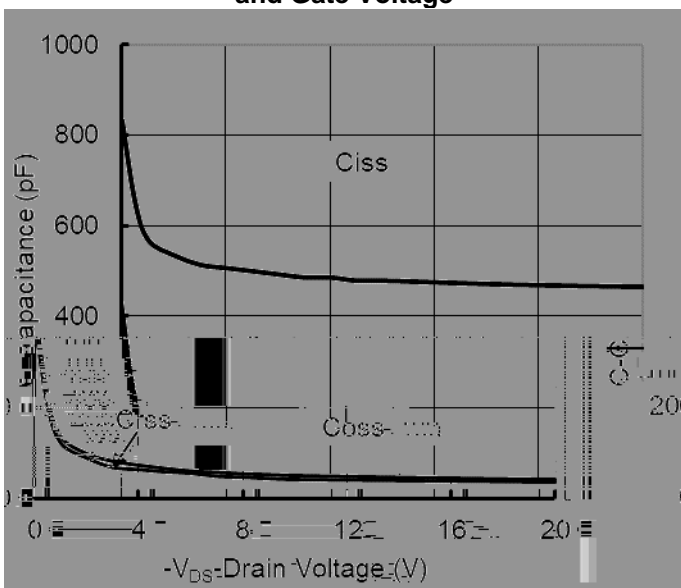


Figure5. Capacitance Characteristics

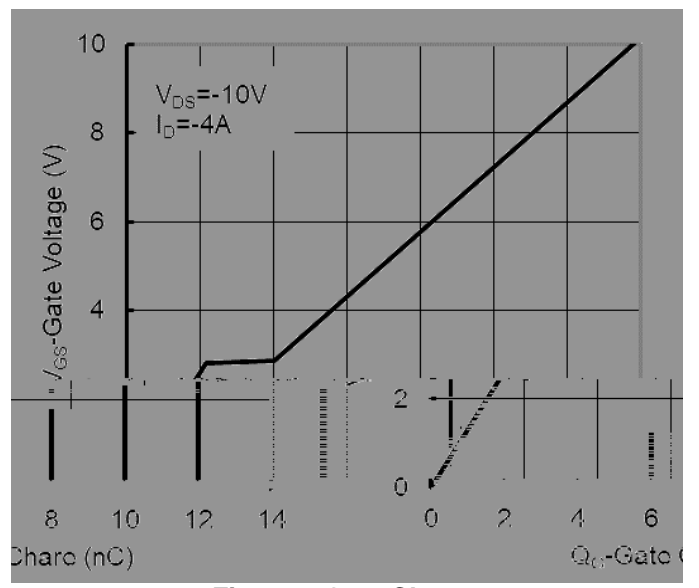
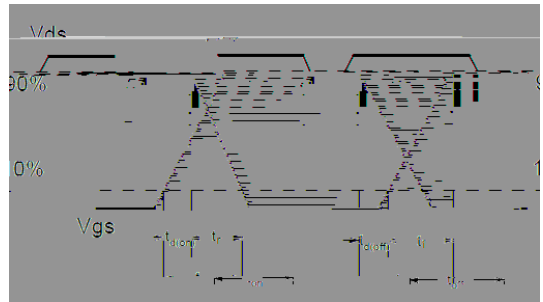
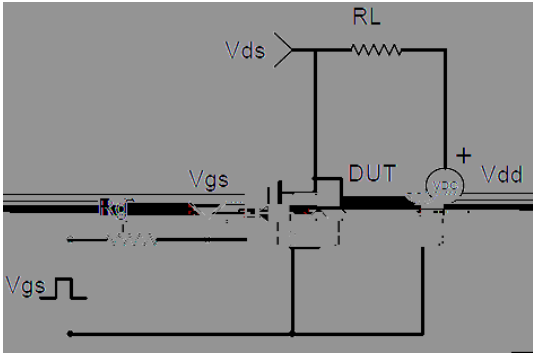


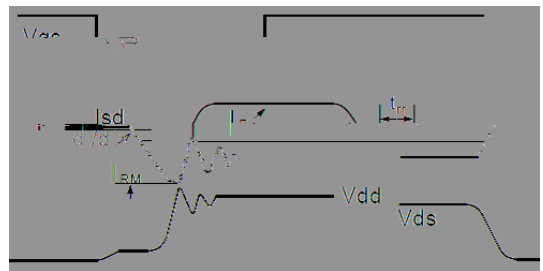
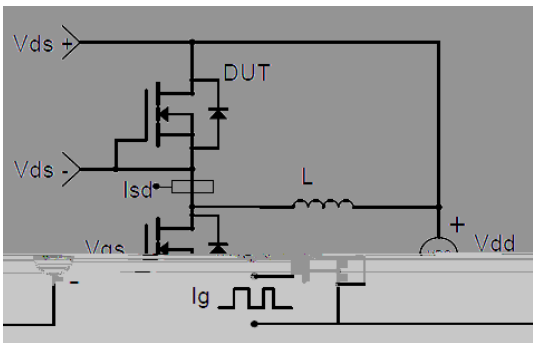
Figure6. Gate Charge

)LJXUH 6DIH 2SHUDWLRQ \$UHD-LJXUH 0D[LPXP &RQWLQXR XV 'UDL
YV \$PELHQW 7HPSHUDWXUH

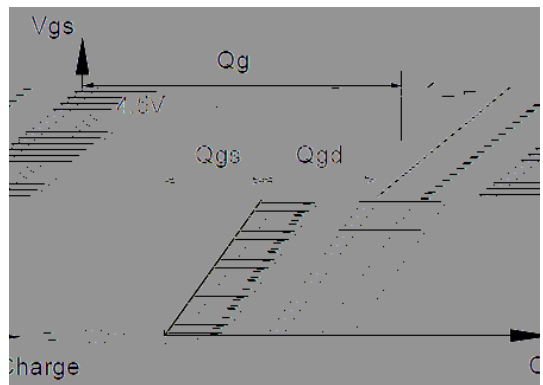
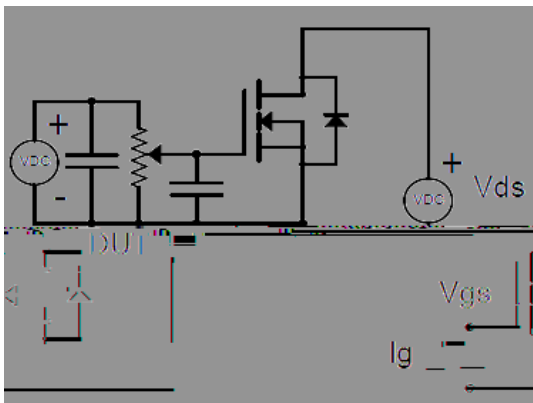
)LJXUH 1RUPDOL]HG DQYLDFW77KHUPDO ,PSHGDQFH



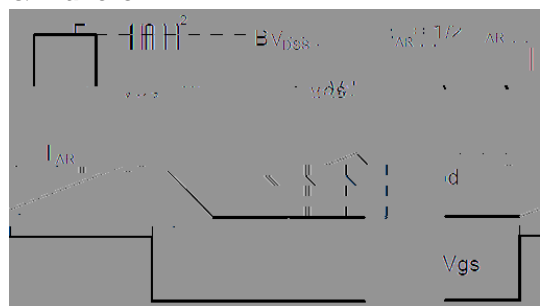
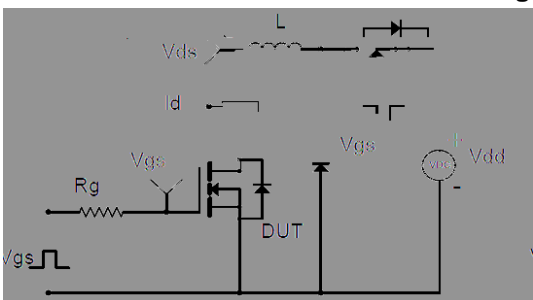
Resistive Switching Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Gate Charge Test Circuit & Waveform



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



SOT-89 Package Information

TYPE A(PACKING CODE:F1):

b	
D1	

YJH03N06B
